

AEC/APC Symposium Asia 2025

Call for Papers

Evolution of AECAPC through Fusion of Domain Knowledge and AI/ML

November 25-26, 2025

FUKUOKA, Japan

<https://www.semiconportal.com/AECAPC/>

Abstract submission start

Monday, May 19, 2025

Abstract submission due

Friday, July 11th, 2025

Notification of acceptance

Monday, September 1, 2025

Presentation materials due

**Only for accepted authors*

Friday, October 31, 2025

AEC/APC (Advanced Equipment Control/Advanced Process Control) Symposium calls its annual conference in North America, Europe, and every other year in Japan.

The suppliers of the device, the equipment, the material, the software, the sensor, and the metrology shall meet, and discuss the more intelligent and the higher productive manufacturing system in the conferences. AEC/APC is called the core of the scientific manufacturing technology. The technology has created the extensive progress of the productivity improvement and the yield improvement in the semiconductor manufacturing area. The technology discussed in the conferences has been applied and used in a variety of technologies.

In Japan, the 10th Anniversary conference is called in this year. The 10th Anniversary AEC/APC Symposium Asia will be held under the theme of **"Evolution of AECAPC through Fusion of Domain Knowledge and AI/ML"** and will be held in a hybrid, with online sessions as the main venue.

Since 2007, the conference has discussed the scientific manufacturing technology using the data which can monitor the manufacturing equipment and the process conditions.

The symposium can also be a very good chance for the professionals of the process control industry such as semiconductor to meet and discuss. The role of this symposium is very important, since people can share the information and the directions of the process control improvement, the equipment productivity improvement, and the material source reduction for the future.

We look forward to seeing you at AEC/APC Symposium Asia 2025!

*AEC: Advanced Equipment Control

*APC: Advanced Process Control

Online Abstract Submission Procedure:

- Prospective authors are requested to submit the abstract through web browser, consisting of exactly two pages of A4-paper size.

-The first page consists of the text (max of 1,000 words) and the second page consists of figures, supporting data, charts, photos and drawings.

- Only PDF files are compatible.

-The abstract must be written in English, using the online abstract submission form (MS word).

Information, templates, and other details are available on the website:

https://www.semiconportal.com/AECAPC/cfp_e.html

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AECAPC Symposium Asia 2025 Area of Interests

Process/Tool Level APC : PTL

- FDC, SPC, Chamber matching, Process monitoring, Predictive control

Sensing : SN

- Sensor development or utilization

Fab Level APC : FAB

- Run to run, Wafer to wafer, Sampling strategy, Defect inspection

Virtual metrology : VM

- Soft sensor, Process models, Reduction of measurement process / non-production wafers

Yield management : YM

- Yield prediction, Yield improvement, Yield modeling and management

Manufacturing effectiveness and productivity : MEP

- Throughput improvement, Productivity improvement, Cost optimization, Maintenance strategy, Production Scheduling

Data analysis : DA

- Bigdata analysis, Novel methods of data analysis and visualisation, AI, Machine learning, Statistical approaches

IT infrastructure : IT

- Infrastructures, Data collection, Standards
- Security

GX(Green Transformation) : GX

- Environmental monitoring, GX using APC

Advanced Packaging and Chiplets Integration: ACH

- 3D bonding, RDL process using APC

APC Strategy / Future needs : APS

- Roadmap, Requirements
- Smart Manufacturing, Digital Twin
- Metaverse, Robotics

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For detail, please visit <https://www.semiconportal.com/AECAPC/>

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